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(71) Applicant: **AXCELIS TECHNOLOGIES, INC.**
[US/US]; 55 Cherry Hill Drive, Beverly, MA 01915-1053
(US).

(72) Inventor: **LAGOS, Bryan**; 120 Pine Street, Danvers, MA
01923 (US).

(74) Agent: **ROBITAILLE, Denis**; Axcelis Technologies,
Inc., 55 Cherry Hill Drive, Beverly, MA 01915-1053 (US).

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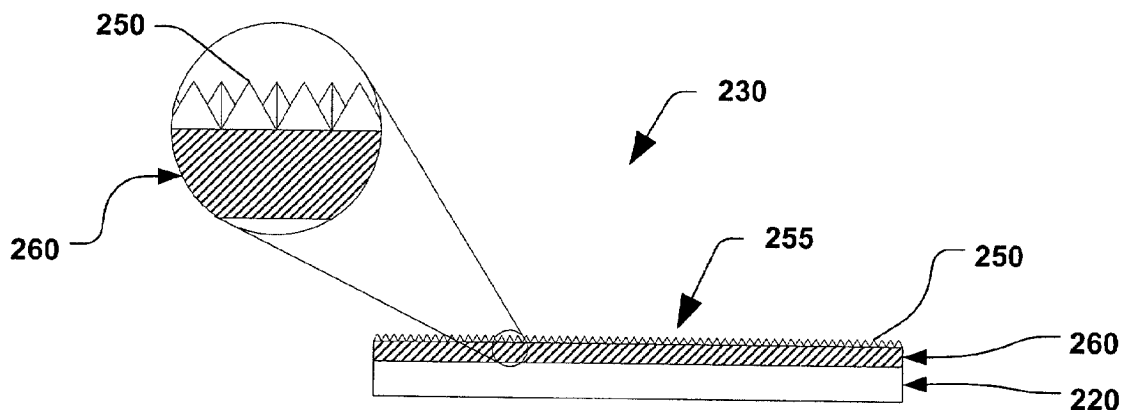
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(54) Title: A METHOD FOR MOLDING A POLYMER SURFACE THAT REDUCES PARTICLE GENERATION AND SUR-
FACE ADHESION FORCES WHILE MAINTAINING A HIGH HEAT TRANSFER COEFFICIENT



(57) Abstract: The invention provides a system and apparatus by which a workpiece pad is supplied to support workpieces being implanted in a rotating or spinning batch implanter process disk. The workpiece pad provides reduced surface adhesion forces and sufficient heat transfer from the workpieces to the process disk, and furthermore reduces particle generation and contamination of the workpiece from the workpiece pad. The workpiece pad furthermore comprises an ordered array of micro-structures. In addition, the invention includes a method of forming a workpiece pad comprising an ordered array of micro-structures.



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